

# DFCH32G14HDHAA

## Part Number/Tape & Reel information

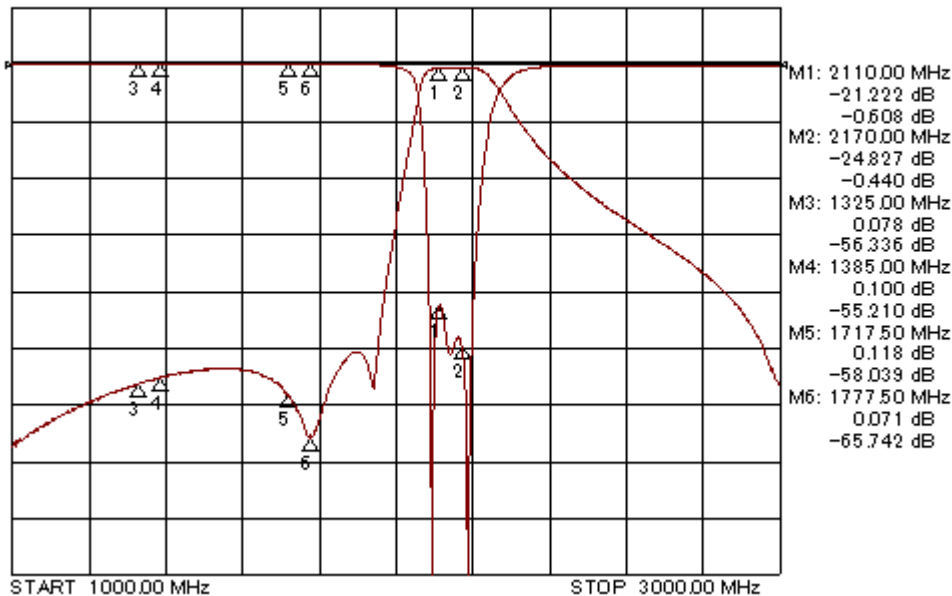
Part Number	Packaging	MOQ
DFCH32G14HDHAA-RF1	330 mm dia. reel	1000 pcs/reel

## Specifications -35 to +85°C

Parameter	IN→OUT	
Center Frequency	F0 : 2140.0 MHz	
Band Width (BW)	F0 ± 30.0 MHz	
Insertion Loss	1.3 dB max.	
Ripple at BW	0.6 dB max.	
V.S.W.R. at BW	1.8 max.	
Input Power	1.0 W max.	
Attenuation	1325 ~ 1385MHz	52dB min.
Absolute value	1717.5 ~ 1777.5MHz	52dB min.
Characteristic Impedance	50Ω	

## Frequency Response

S11 logMAG 5dB/REF0dB  
S21 logMAG 10dB/REF0dB

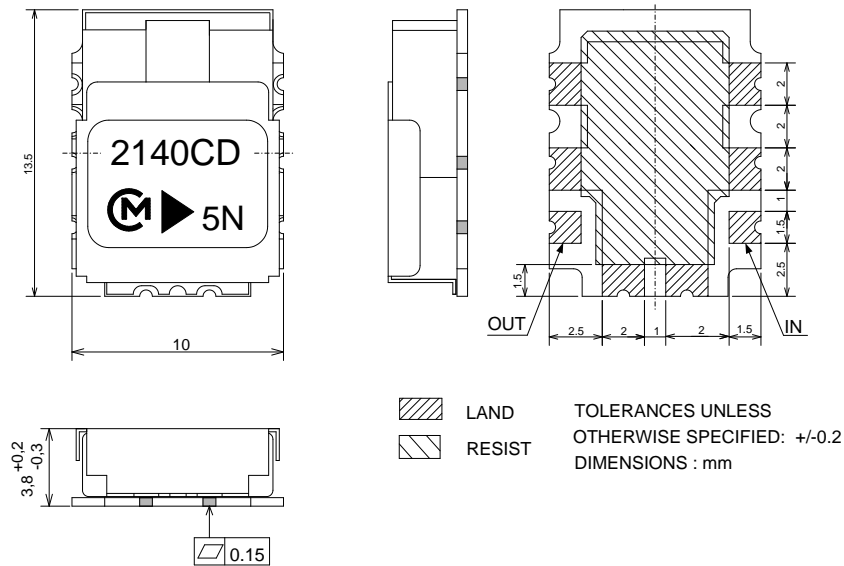


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\*Note: All the technical data and information contained herein are subject to change without advanced notice.

# DFCH32G14HDHAA

## Dimensions and Marking

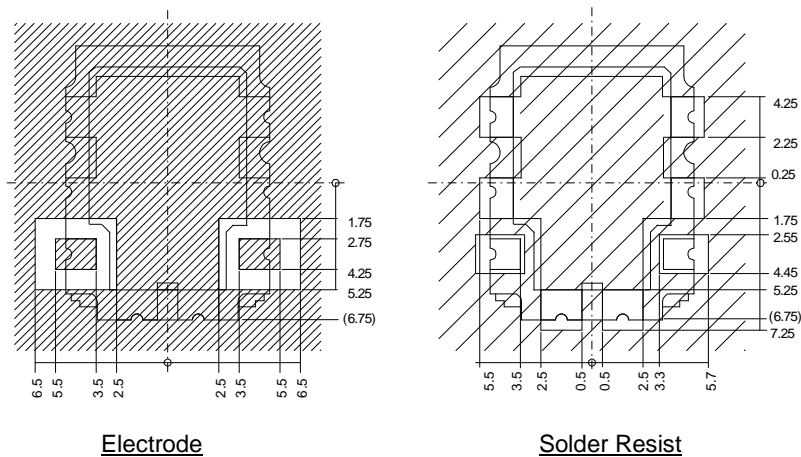


NOTE : Construction of Number

LOT NO : 5N 5 : Year

N: Month (1 to 9, Oct.-O, Nov.-N, Dec.-D)

## Recommend Land Pattern (reference)



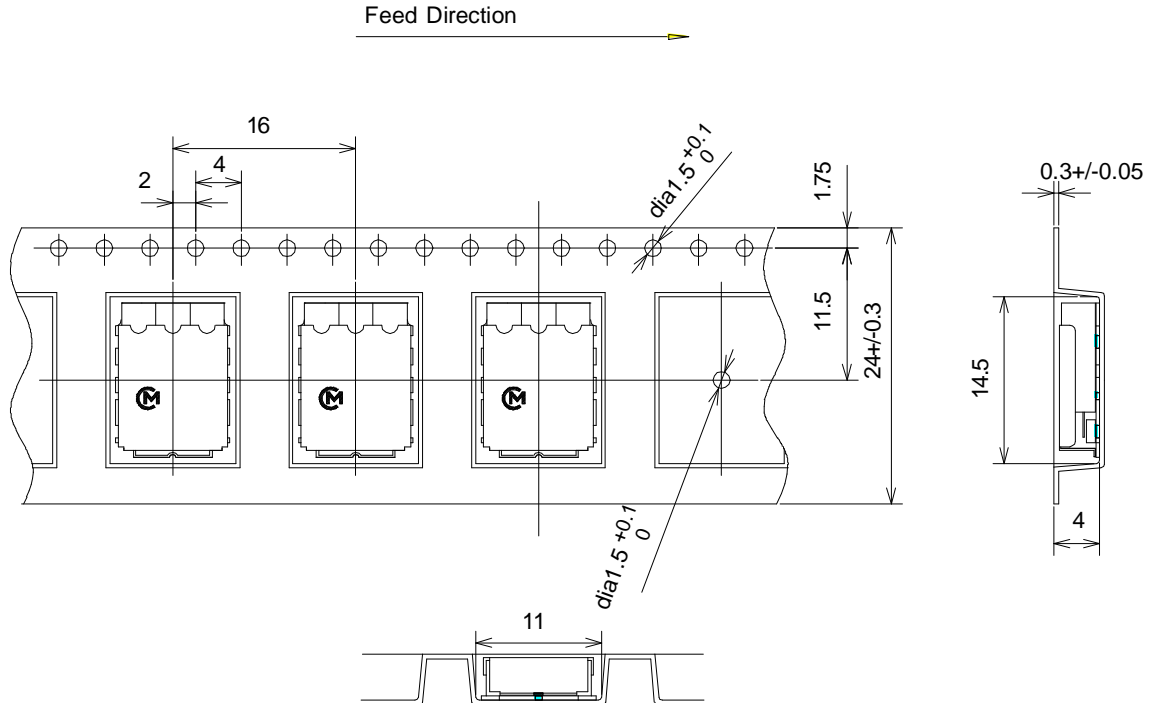
Note : Impedance of signal lines should be 50 ohms including land pattern. This standard condition is applying to the glass epoxy board (t = 1.0mm, dielectric constant = 4.8, copper plating on both surfaces) and the land patterns are connected to 50 ohms micro-strip lines on back side surface through the via hole.

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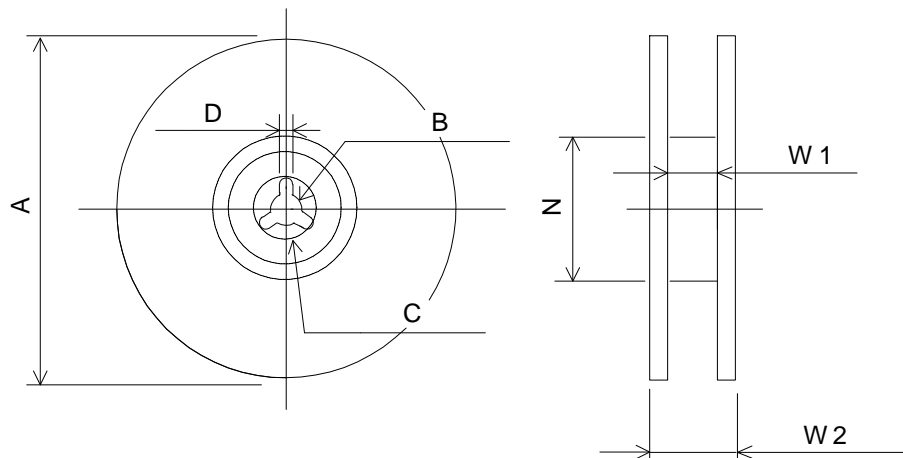
# DFCH32G14HDHAA

## Dimensions of Carrier Tape



TOLERANCES UNLESS  
OTHERWISE SPECIFIED : +/-0.1  
DIMENSIONS : mm

## Dimensions of Reel



Murata Part Number	A+/-2.0	B+/-0.5	C+/-0.8	D+/-0.5	N (min.)	W1+/-1.5	W2 (max.)
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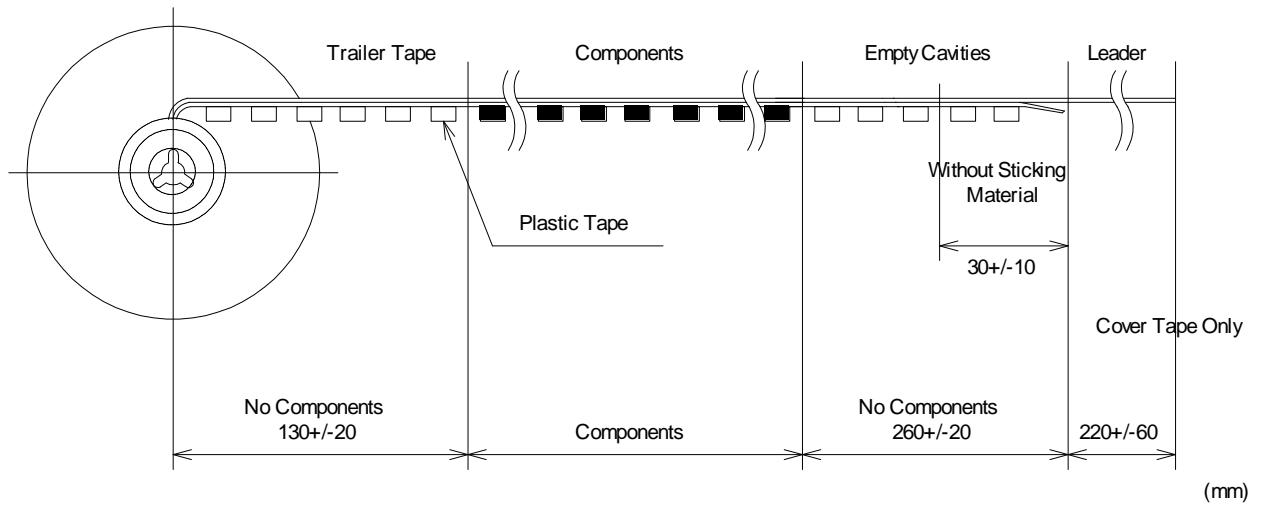
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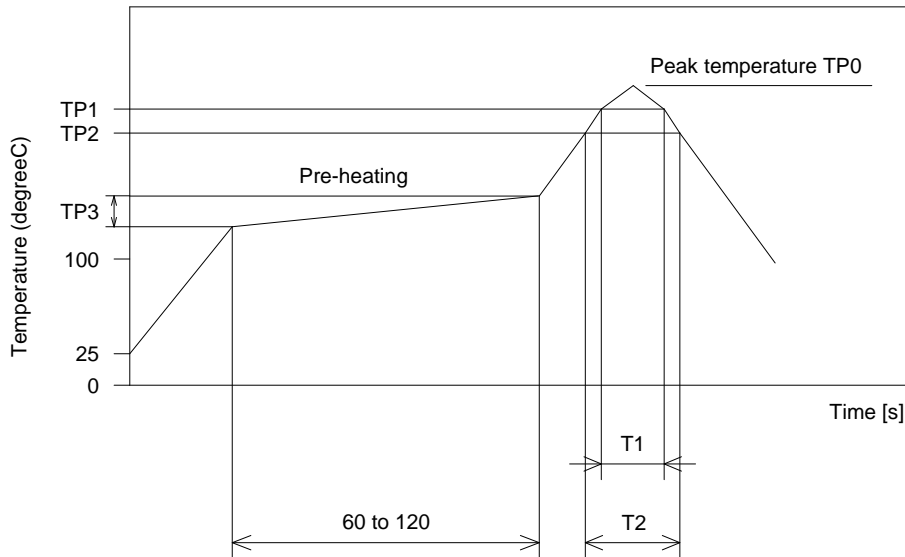
DFCH32G14HDHAA-RF1	φ 330	φ 13	φ 21	2	φ 50	25.5	31
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## Taping Condition



# DFCH32G14HDHAA

## Reflow Soldering Standard Conditions



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

		TP0 (°C )	TP1 (°C )	T1 (s)	TP2 (°C )	T2 (s)	TP3 (°C )
Reflow standard condition	Sn-40Pb solder	225+/-5	200	20 to 40	---	---	140 to 160
	Sn-3Ag-0.5Cu solder	245+/-5	220	30 to 60	---	---	150 to 180
Test condition of reflow heat resistance		260+5/-0	240	20	220	70	150 to 180

## Allowable Temperature and Time of Reflow Soldering

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